R2ABF~R2MBF 2.0Amp Surface Mount Fast Recovery Rectifiers

Features

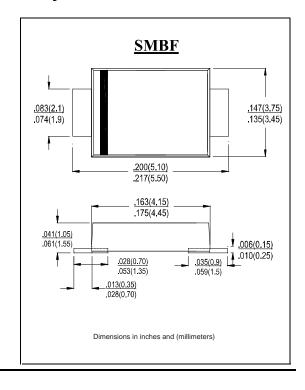
- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Fast switching for high efficiency
- ◆ Low reverse leakage
- ◆ Built-in strain relief,ideal for automated placement
- High forward surge current capability
- ◆ High temperature soldering guaranteed: 260°C/10 seconds at terminals
- Glass passivated chip junction

Mechanical Data

Case: JEDEC SMBF molded plastic body over passivated chip Terminals: Solder plated, solderable per MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end

Mounting Position: Any



Maximum Ratings And Electrical Characteristics

Ratings at 25° C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

	SYMBOLS	R2ABF	R2BBF	R2DBF	R2GBF	R2JBF	R2KBF	R2MBF	UNITS
Maximum repetitive peak reverse voltage	VRRM	50	100	200	400	600	800	1000	VOLTS
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	VOLTS
Maximum DC blocking voltage	VDC	50	100	200	400	600	800	1000	VOLTS
Maximum average forward rectified current at TL=90°C	I _(AV)	2.0							Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	IFSM	50.0						Amps	
Maximum instantaneous forward voltage at 2.0A	VF	1.3							Volts
Maximum DC reverse current TA=25℃ at rated DC blocking voltage TA=100℃	IR	5.0 50.0						μΑ	
Maximum reverse recovery time (NOTE 1)	trr		15	50		250	50	00	ns
Typical junction capacitance (NOTE 2)	CJ	50.0							pF
Typical thermal resistance (NOTE 3)	RθJA	20.0							°C/W
Operating junction and storage temperature range	Т _J ,Т _{STG}	-65 to +150							°C

Note: 1. Reverse recovery condition IF=0.5A, IR=1.0A, Irr=0.25A

- 2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.
- 3.P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas